



### 1000V N-ch Planar MOSFET

Lead Free Package and Finish

#### General Features

- RoHS Compliant
- $R_{DS(ON),typ.}=2.0\ \Omega@V_{GS}=10V$
- Low Gate Charge Minimize Switching Loss
- Fast Recovery Body Diode

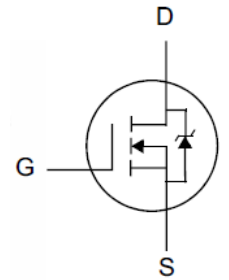
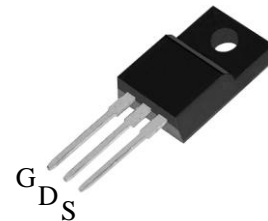
$BV_{DSS}$	$R_{DS(ON),typ.}$	$I_D$
1000V	2.0Ω	4.0A

#### Applications

- Adaptor
- Charger
- SMPS Standby Power

#### Ordering Information

Part Number	Package	Brand
PTA04N100	TO-220F	



TO-220F

Package No to Scale

#### Absolute Maximum Ratings

$T_C=25^{\circ}C$  unless otherwise specified

Symbol	Parameter	PTA04N100	Unit
$V_{DSS}$	Drain-to-Source Voltage	1000	V
$V_{GSS}$	Gate-to-Source Voltage	±30	
$I_D$	Continuous Drain Current	4.0	A
$I_{DM}$	Pulsed Drain Current at $V_{GS}=10V$	16	
$E_{AS}$	Single Pulse Avalanche Energy	450	mJ
$P_D$	Power Dissipation	33	W
	Derating Factor above 25°C	0.26	W/°C
$T_L$	Soldering Temperature Distance of 1.6mm from case for 10 seconds	300	°C
$T_J \& T_{STG}$	Operating and Storage Temperature Range	-55 to 150	

Caution: Stresses greater than those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device.

#### Thermal Characteristics

Symbol	Parameter	PTA04N100	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	3.78	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	100	



## Electrical Characteristics

### OFF Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$BV_{DSS}$	Drain-to-Source Breakdown Voltage	1000	--	--	V	$V_{GS}=0V, I_D=250\mu A$
$I_{DSS}$	Drain-to-Source Leakage Current	--	--	1	$\mu A$	$V_{DS}=1000V, V_{GS}=0V$
		--	--	100		$V_{DS}=800V, V_{GS}=0V, T_J=125^\circ\text{C}$
$I_{GSS}$	Gate-to-Source Leakage Current	--	--	+100	$nA$	$V_{GS}=+30V, V_{DS}=0V$
		--	--	-100		$V_{GS}=-30V, V_{DS}=0V$

### ON Characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$R_{DS(ON)}$	Static Drain-to-Source On-Resistance	--	2.0	2.5	$\Omega$	$V_{GS}=10V, I_D=2A$
$V_{GS(TH)}$	Gate Threshold Voltage	3.0	--	5.0	V	$V_{DS}=V_{GS}, I_D=250\mu A$
gfs	Forward Transconductance	--	4.5	--	S	$V_{DS}=15V, I_D=2A$

### Dynamic Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$C_{iss}$	Input Capacitance	--	1470	--	$pF$	$V_{GS}=0V, V_{DS}=25V, f=1.0MHz$
$C_{rss}$	Reverse Transfer Capacitance	--	21	--		
$C_{oss}$	Output Capacitance	--	115	--		
$Q_g$	Total Gate Charge	--	36	--	$nC$	$V_{DD}=500V, I_D=4A, V_{GS}=0 \text{ to } 10V$
$Q_{gs}$	Gate-to-Source Charge	--	7.5	--		
$Q_{gd}$	Gate-to-Drain (Miller) Charge	--	14	--		

### Resistive Switching Characteristics

Essentially independent of operating temperature

Symbol	Parameter	Min.	Typ.	Max.	Unit	Test Conditions
$t_{d(ON)}$	Turn-on Delay Time	--	20	--	$nS$	$V_{DD}=500V, I_D=4A, V_{GS}=10V, R_g=4.7\Omega$
$t_{rise}$	Rise Time	--	23	--		
$t_{d(OFF)}$	Turn-Off Delay Time	--	28	--		
$t_{fall}$	Fall Time	--	26	--		

**Source-Drain Body Diode Characteristics** $T_J=25^{\circ}\text{C}$  unless otherwise specified

Symbol	Parameter	Min	Typ.	Max.	Unit	Test Conditions
$I_{SD}$	Continuous Source Current <sup>[2]</sup>	--	--	4	A	Integral pn-diode in MOSFET
$I_{SM}$	Pulsed Source Current <sup>[2]</sup>	--	--	16		
$V_{SD}$	Diode Forward Voltage	--	--	1.5	V	$I_S=4\text{A}$ , $V_{GS}=0\text{V}$
$t_{rr}$	Reverse Recovery Time	--	320	--	ns	$V_{GS}=0\text{V}$ $I_F=I_S$ , $di/dt=100\text{A}/\mu\text{s}$
$Q_{rr}$	Reverse Recovery Charge	--	1.00	--	$\mu\text{C}$	

**Note:**[1]  $T_J=+25^{\circ}\text{C}$  to  $+150^{\circ}\text{C}$ [2] Pulse width $\leq 380\mu\text{s}$ ; duty cycle $\leq 2\%$ .



### Typical Characteristics

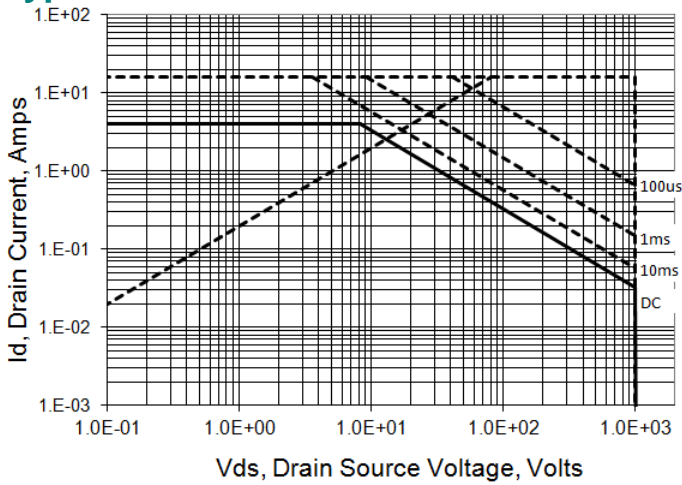


Figure 1 . Maximum Safe Operating Area

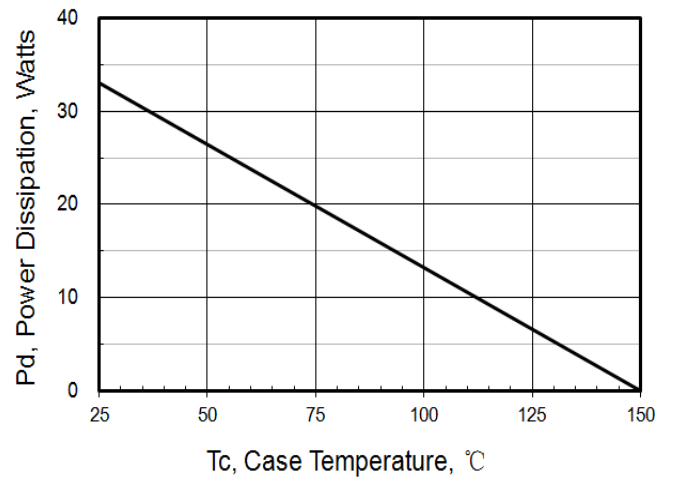


Figure 2 . Maximum Power Dissipation vs Tc

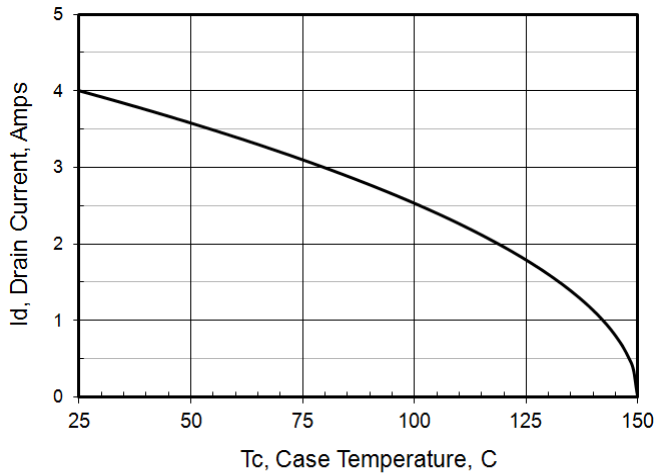


Figure 3 .Id vs Case Temperature

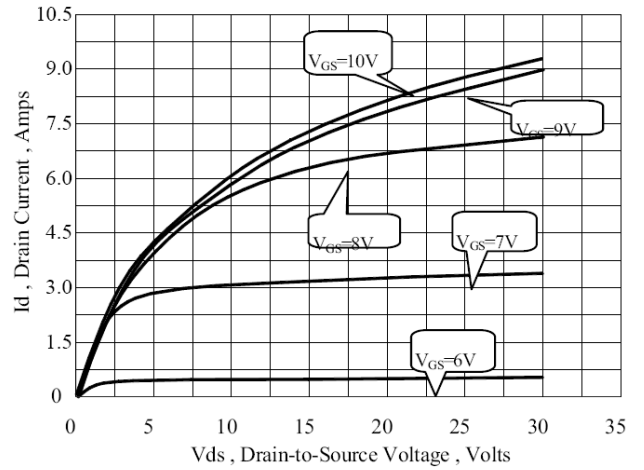


Figure 4 Typical Output Characteristics

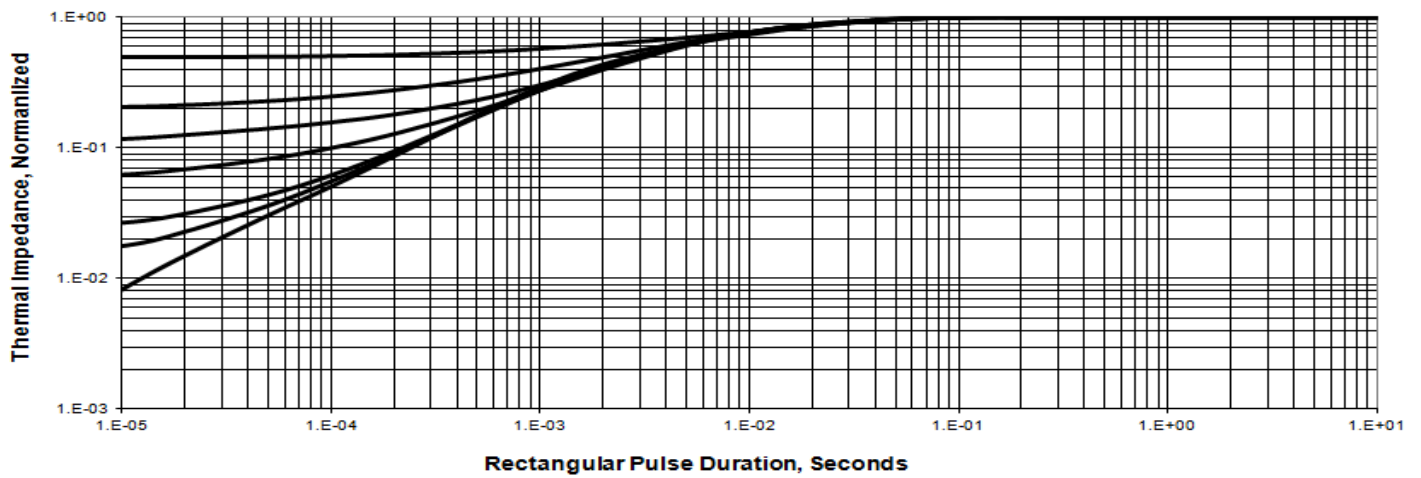


Figure 5. Maximum Transient Thermal Impedance



### Typical Characteristics(Cont.)

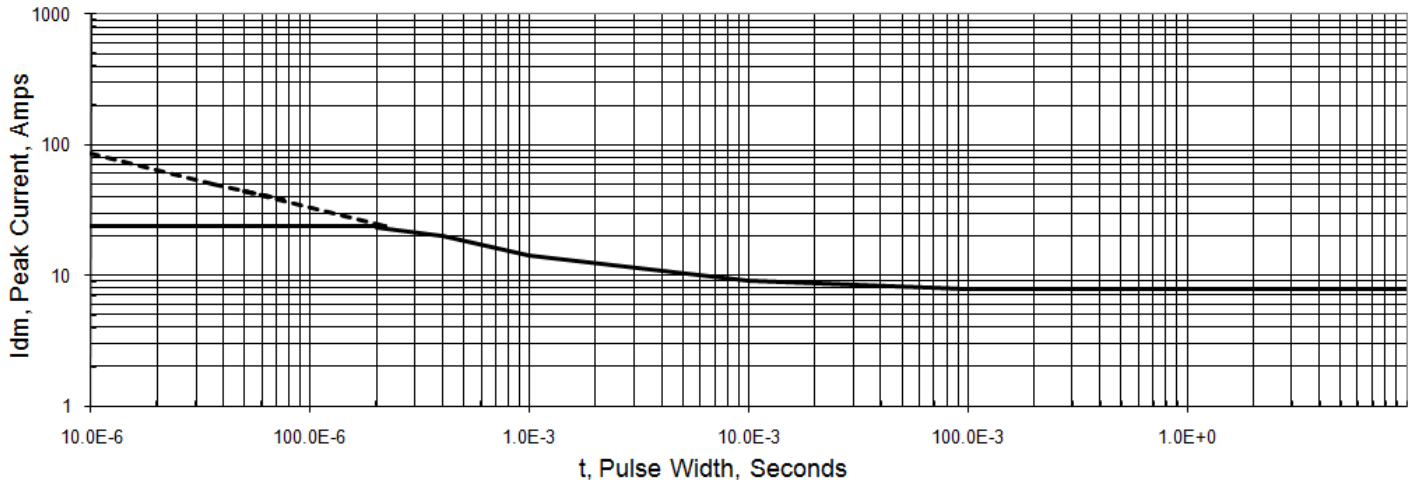


Figure 6. Peak Current Capability

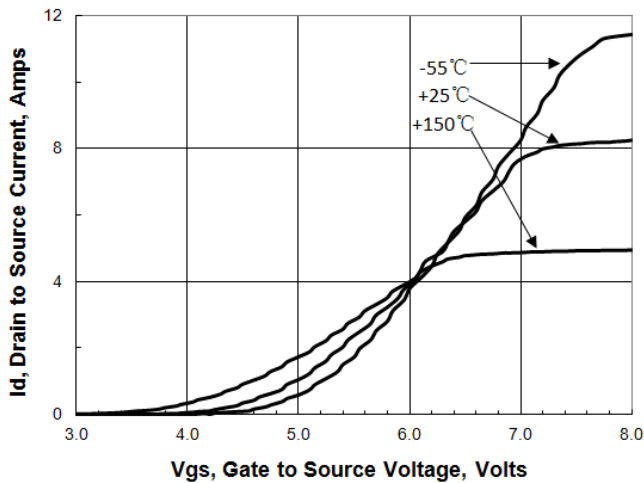


Figure 7. Transfer Characteristics

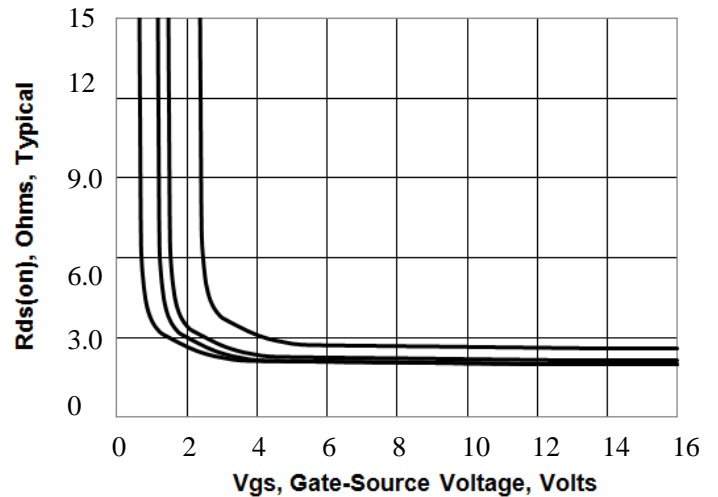


Figure 5. RDSON vs Gate Voltage

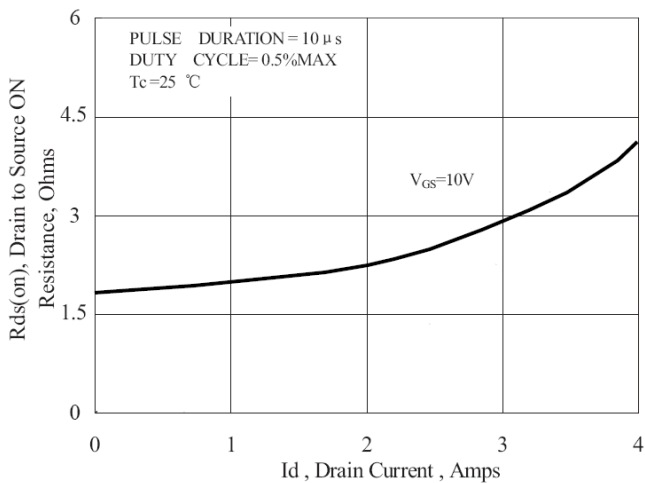


Figure 9 Typical Drain to Source ON Resistance vs Drain Current

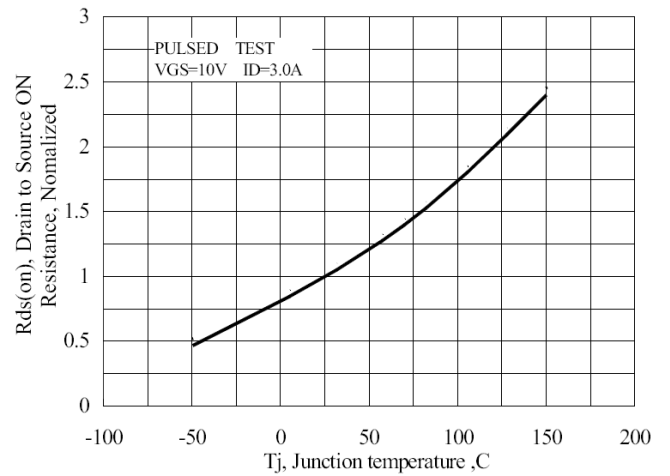


Figure 10 Typical Drain to Source on Resistance vs Junction Temperature



### Typical Characteristics(Cont.)

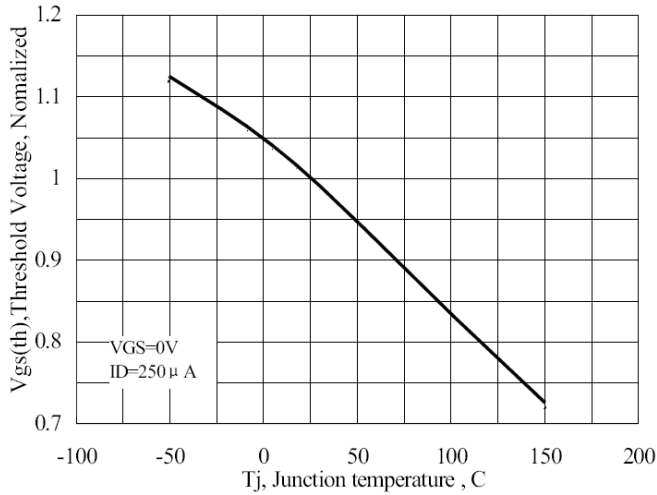


Figure 11 Typical Threshold Voltage vs Junction Temperature

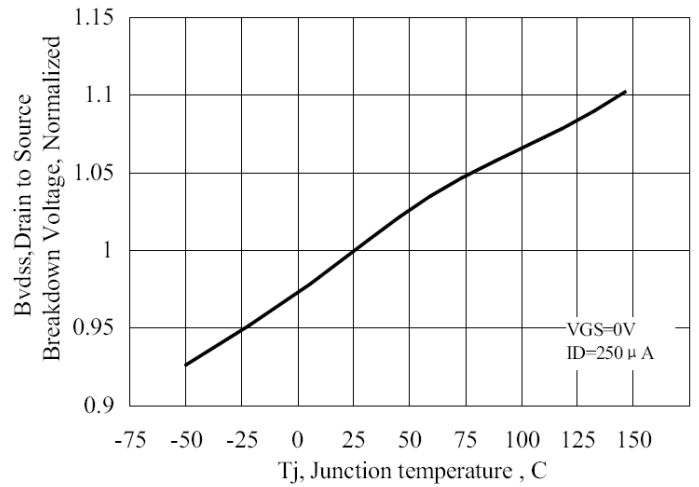


Figure 12 Typical Breakdown Voltage vs Junction Temperature

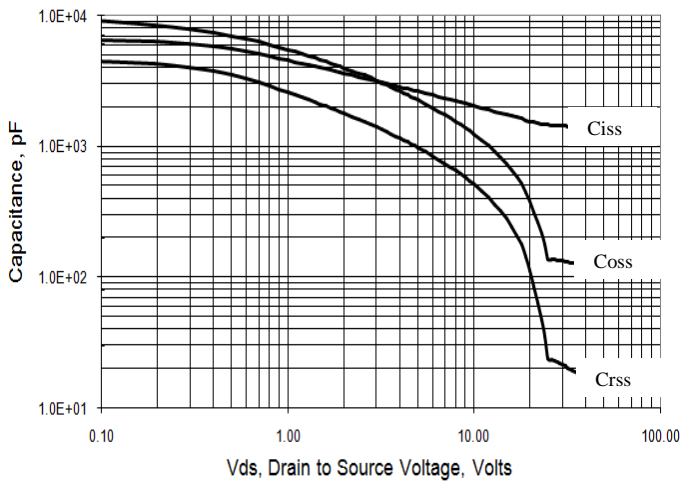


Figure 13. Capacitance vs Vds

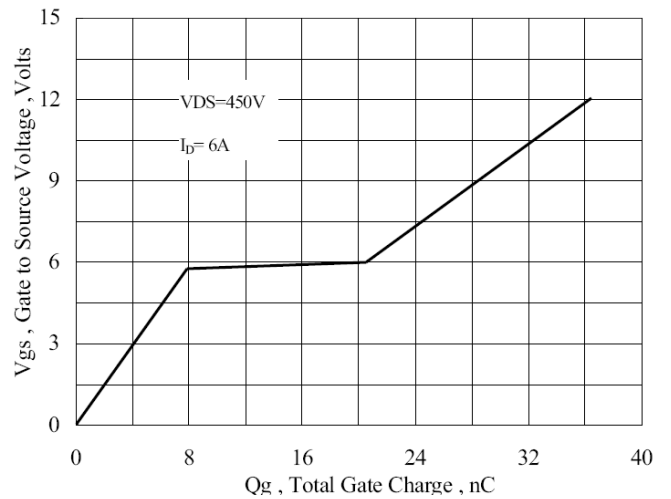


Figure 14 Typical Gate Charge vs Gate to Source Voltage

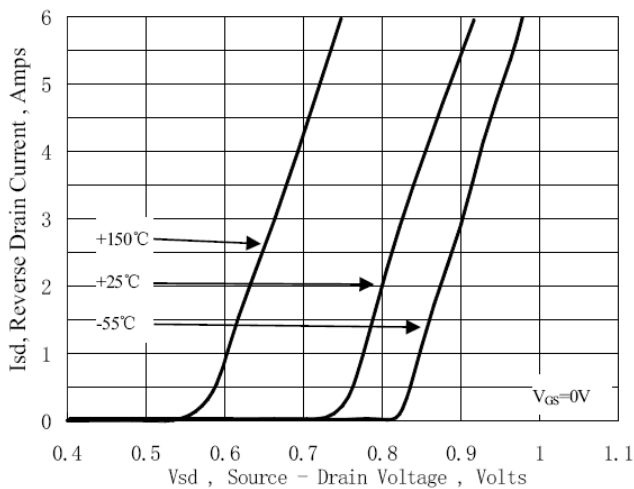


Figure 15 Typical Body Diode Transfer Characteristics

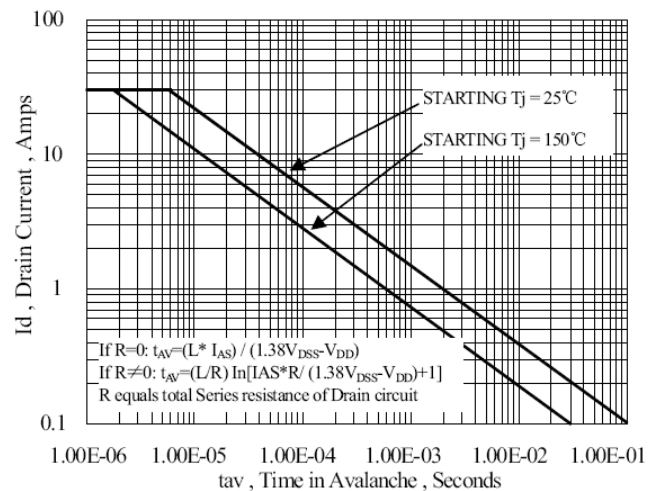


Figure 16 Unclamped Inductive Switching Capability

## Test Circuits and Waveforms

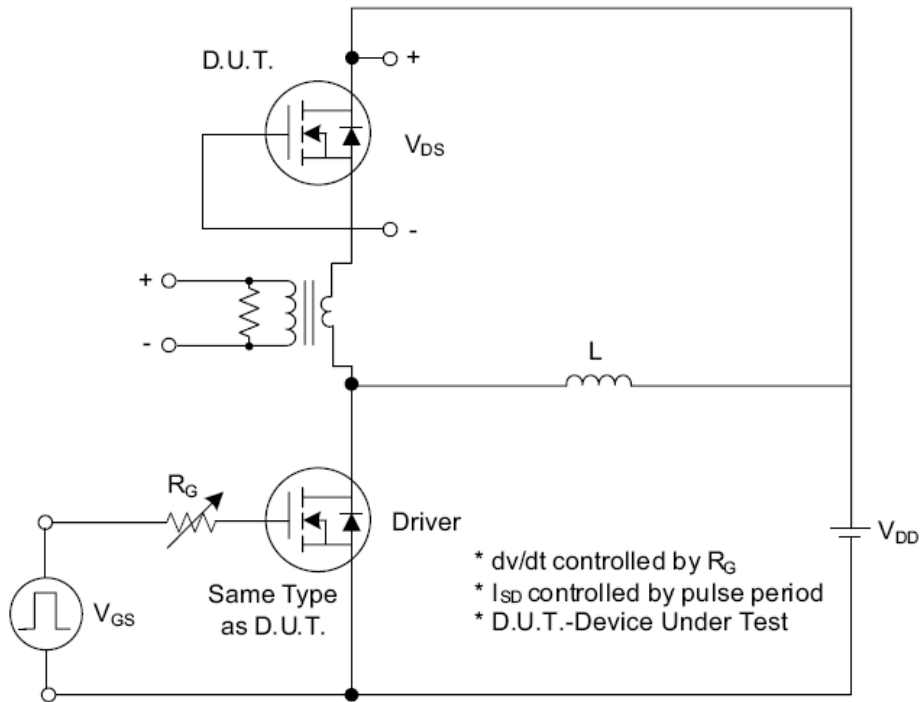


Fig. 1.1 Peak Diode Recovery  $dv/dt$  Test Circuit

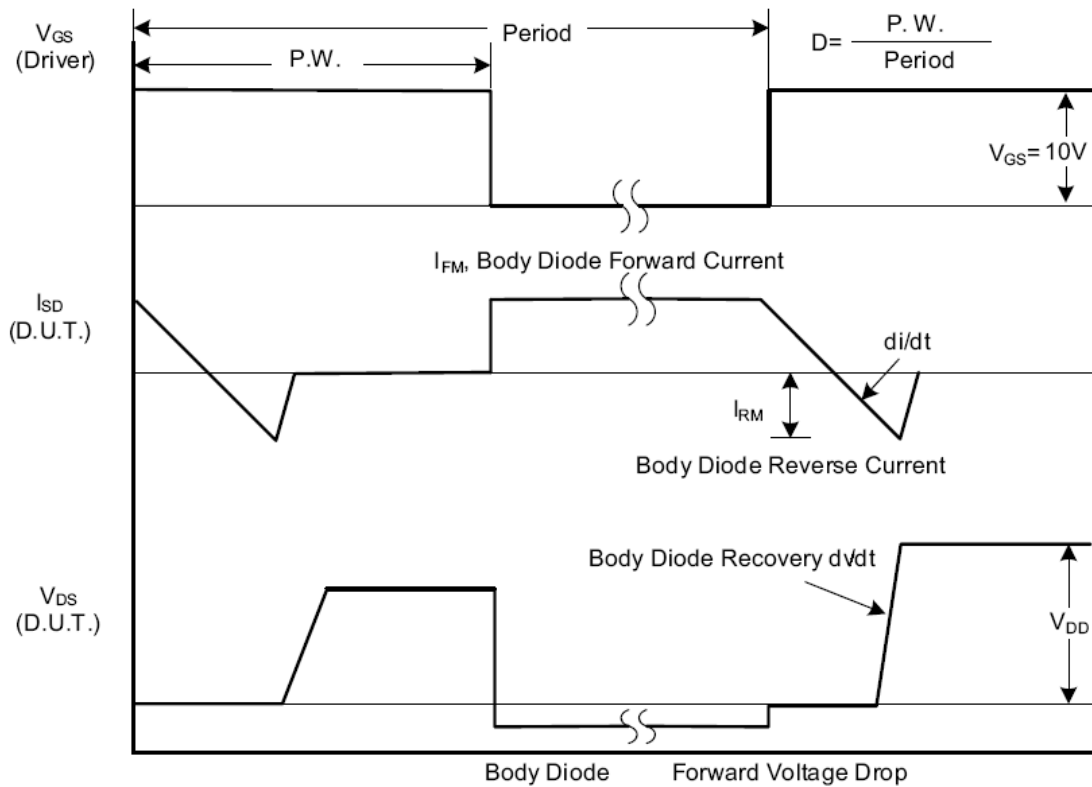


Fig. 1.2 Peak Diode Recovery  $dv/dt$  Waveforms

Test Circuits and Waveforms (Cont.)

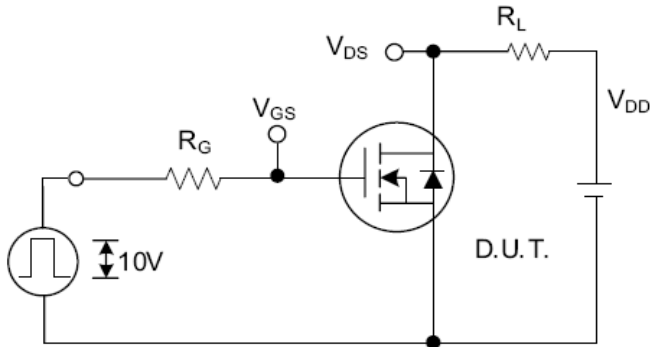


Fig. 2.1 Switching Test Circuit

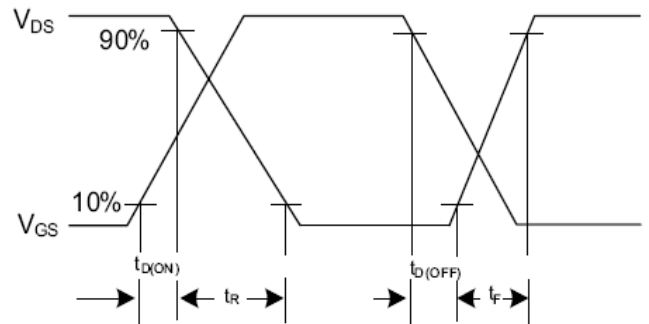


Fig. 2.2 Switching Waveforms

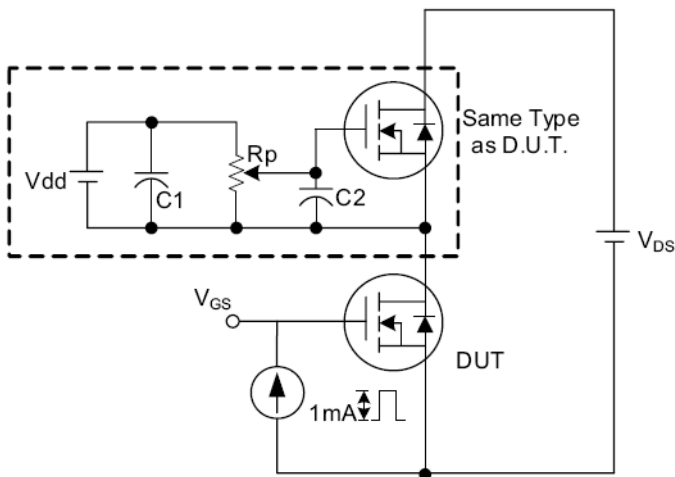


Fig. 3.1 Gate Charge Test Circuit

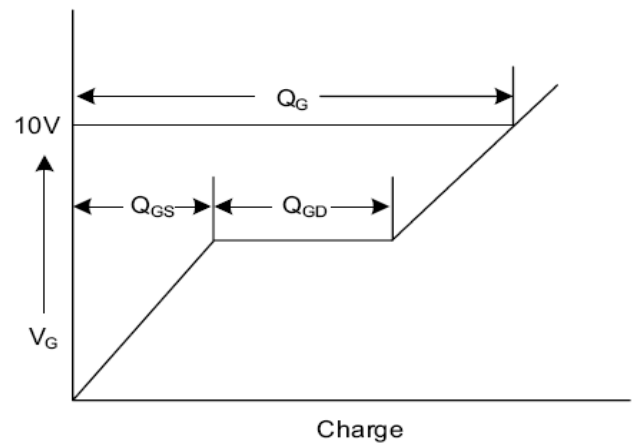


Fig. 3.2 Gate Charge Waveform

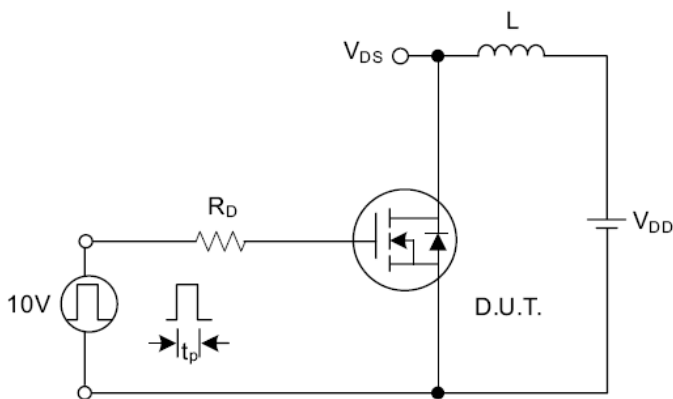


Fig. 4.1 Unclamped Inductive Switching Test Circuit

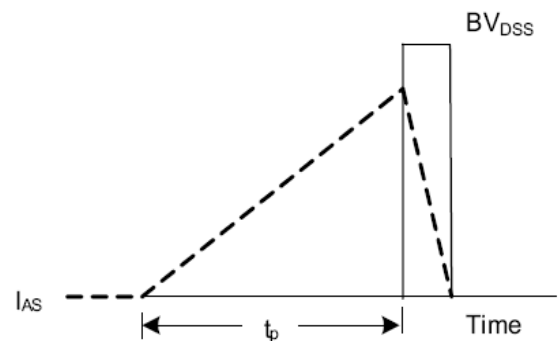


Fig. 4.2 Unclamped Inductive Switching Waveforms





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